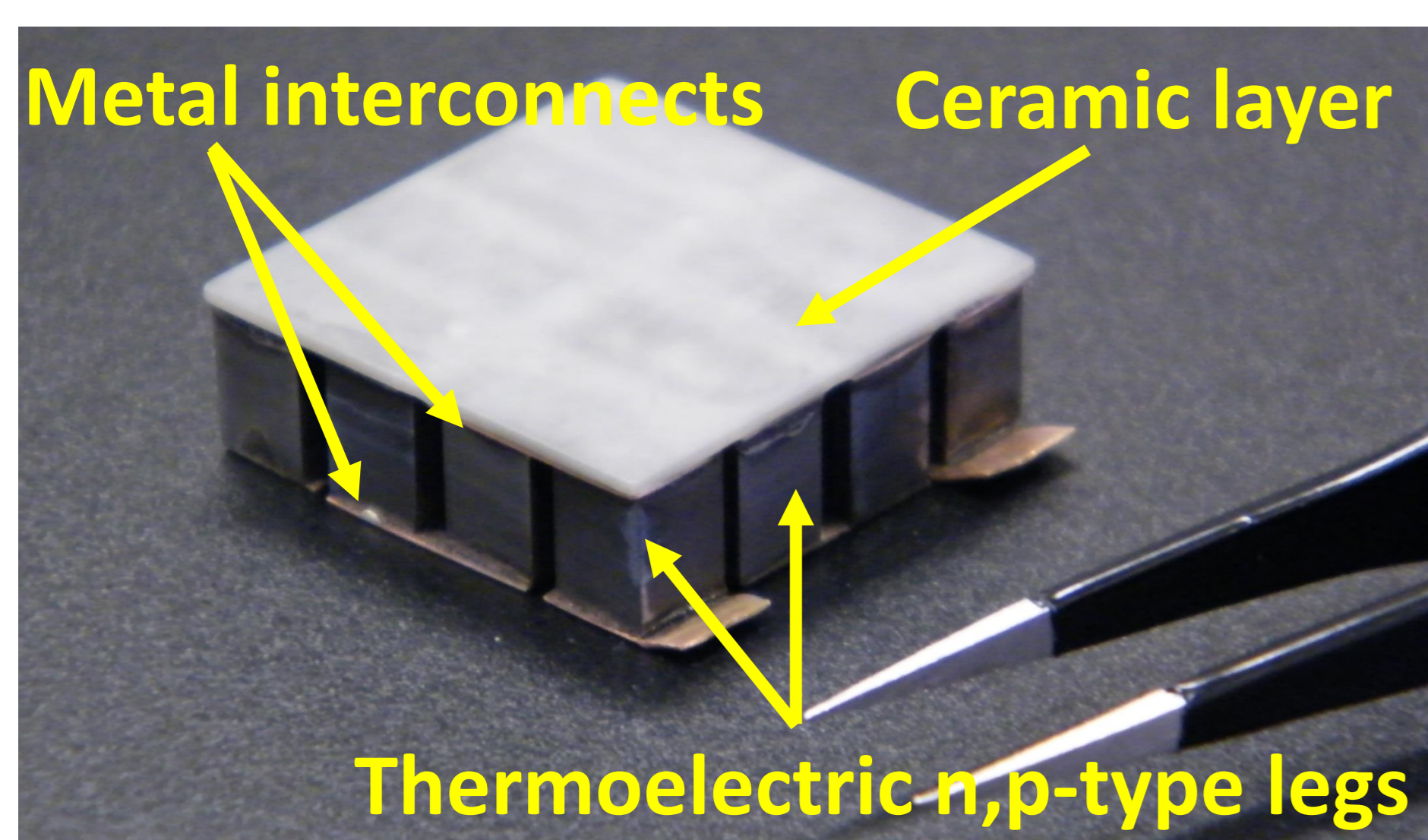


# Finite Element Evaluation of the Strength of Silicide-Based Thermoelectric Modules

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**Introduction:** Silicide-based thermoelectric modules (TEMs) for power generation operate at mid-high temperature range. In the operating conditions, thermal stresses in materials with different coefficient of thermal expansion may reduce the mechanical strength of the modules. In this work, a finite element (FE) evaluation of the mechanical strength of a 16 legs thermoelectric module prototype (Figure 1) operating with 300 K temperature difference is presented.



**Figure 1.** Prototype of the 16 legs silicide-based TEM. Heat flows from the top ( $T_h$ ) to the bottom ( $T_c$ ) side.

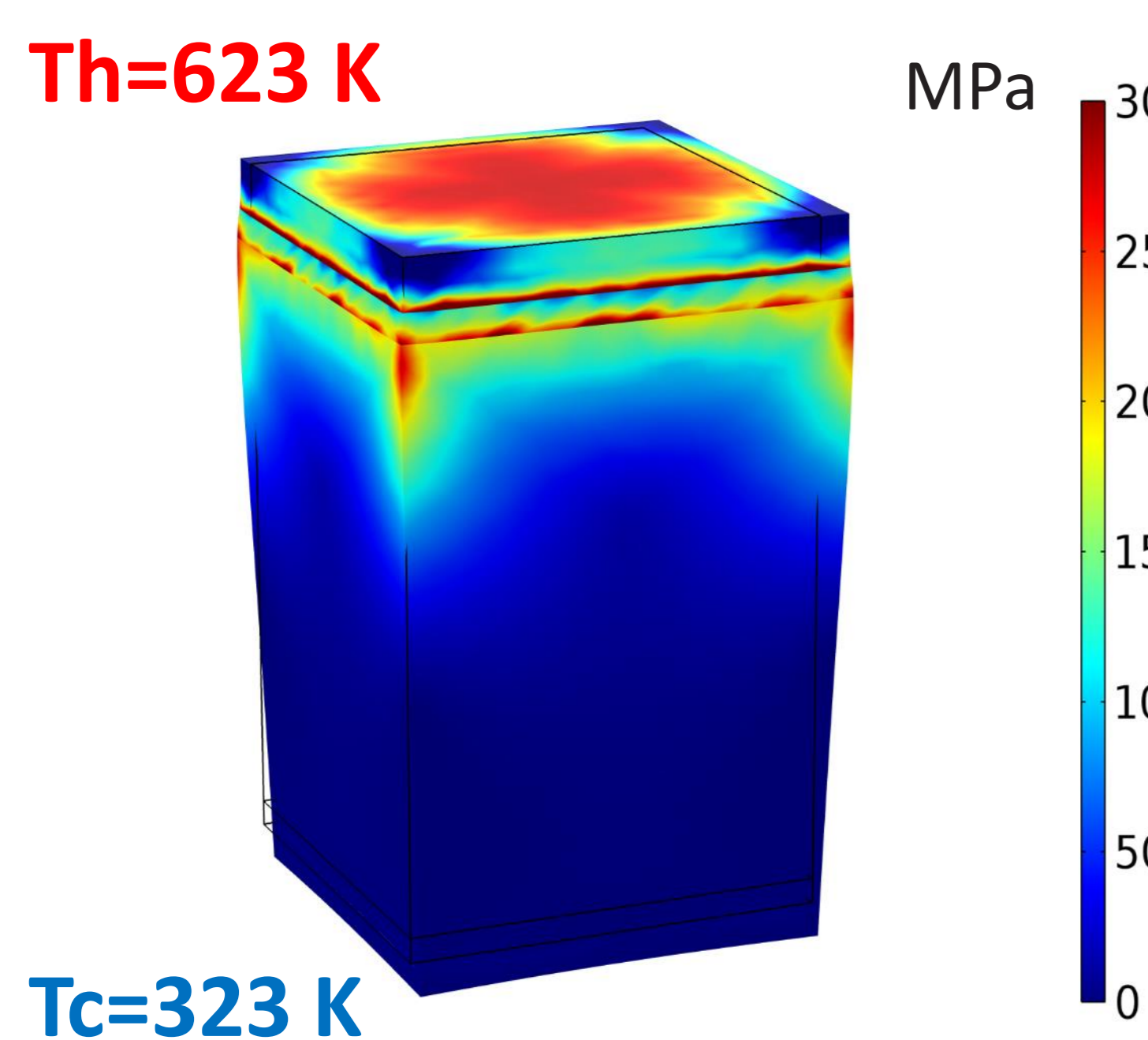
**Computational Methods:** In the simulation, the thermoelectric module has been evaluated in open-circuit conditions, i.e. only conduction contribution was considered for heat flux (no Peltier or Joule effect taken into account).

COMSOL® Heat transfer in solids and Solid mechanics interfaces have been coupled considering:

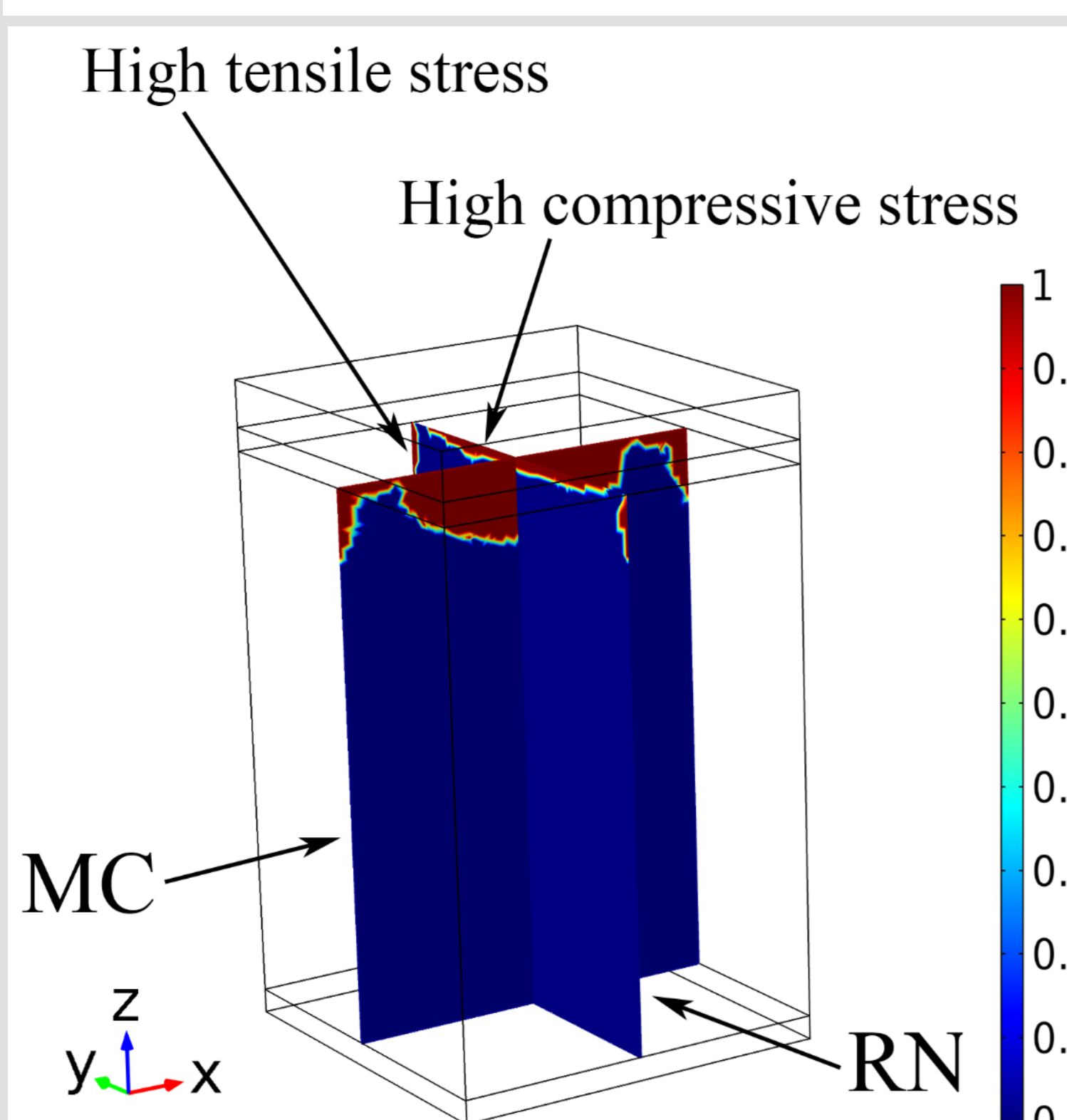
$$\begin{aligned} \nabla \cdot (-k\nabla T) &= 0 \\ \nabla \cdot S + F_v &= 0 \\ S &= C : (\epsilon - \epsilon_{th}) \\ \epsilon &= \frac{1}{2} (\nabla \mathbf{u} + (\nabla \mathbf{u})^T) \\ \epsilon_{in} &= \epsilon_0 + \epsilon_{th} \end{aligned}$$

being  $\epsilon_{th}$  the thermal expansion coefficients of components and  $T_c$  the cold side temperature.

$$\epsilon_{th} = \alpha_{th}(T - T_c)$$



**Figure 2.** Evaluation of maximum tensile stress on a single n-type leg ( $\Delta T=300$  K) with top/bottom metal connections and top ceramic layer. Thermal expansion leads to high stress on the hot side.



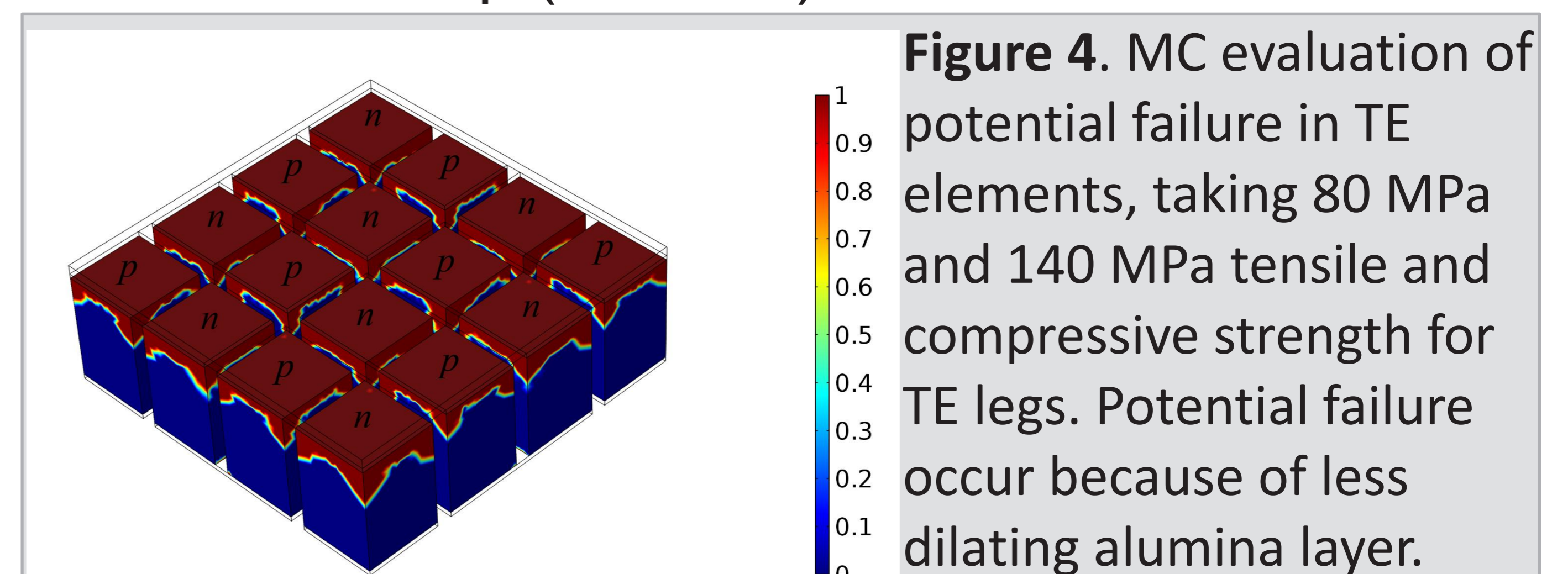
**Figure 3.** Evaluation of failure of a single n-type leg with Mohr-Coulomb (MC, xz-plot) and Rankine (RN, yz-plot) criteria. Blue (0) depicts the elastic region, dark red (1) depicts plastic/failure region. Mohr-Coulomb criterion leads to wider failure region, since it sets a more strict condition on stress.

**Results:** In the simulation, mechanical properties of materials have been taken as follows:

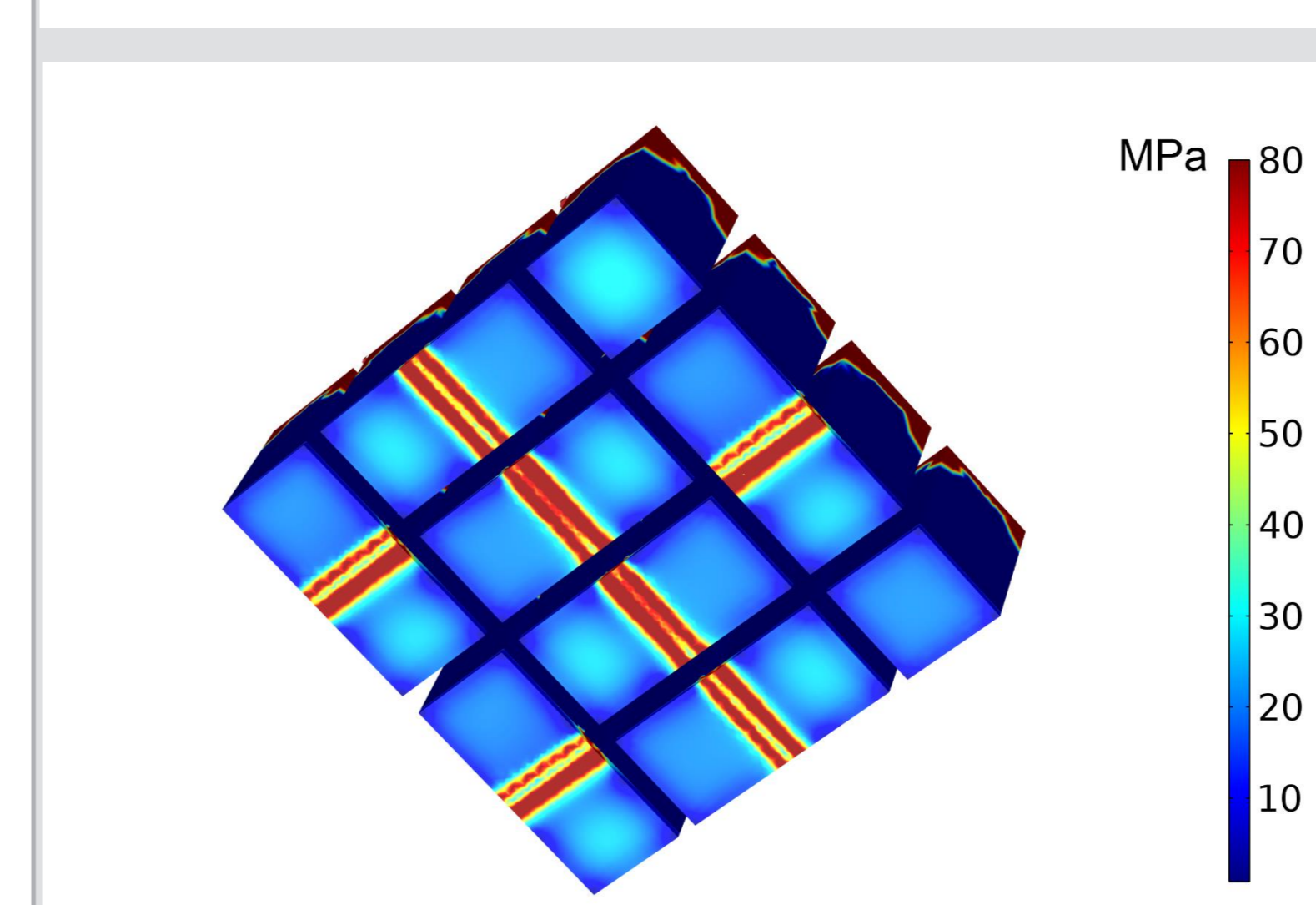
	Young's Modulus $E$ [GPa]	Poisson's ratio $\nu$	CTE ( $\alpha_{th}$ ) [1/K]
Sb-doped $Mg_2Si$ ( $n$ -type legs)	116	0.18	$15.0 \times 10^{-6}$
HMS ( $p$ -type legs)	245	0.2	$11.1 \times 10^{-6}$
Cu connections	110	0.35	$17.0 \times 10^{-6}$
Alumina (top ceramic layer)	300	0.22	$8.0 \times 10^{-6}$

**Table 3.** Elastic properties and CTE values of materials.

Mohr-Coulomb (*failure*) and Von Mises (*yield*) criteria have been considered for thermoelectric legs and metal interconnects respectively. Failure on thermoelectric legs was found to occur on the top (hot side).

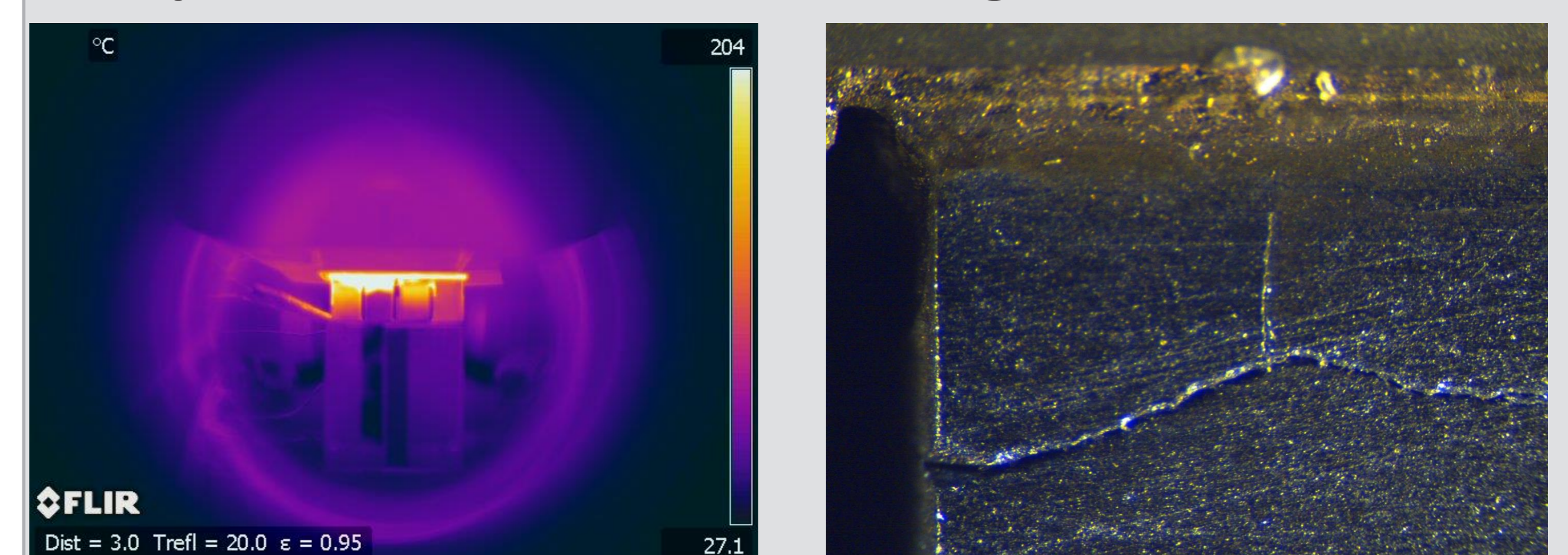


**Figure 4.** MC evaluation of potential failure in TE elements, taking 80 MPa and 140 MPa tensile and compressive strength for TE legs. Potential failure occur because of less dilating alumina layer.



**Figure 5.** Yielding of bottom Cu connections is due to different longitudinal expansion of n,p-type legs.

## Comparison with module testing results



**Figure 6.** Cracks occurring on the top of n-type legs was observed also through IR Thermography on the tested prototype (a). Detail of crack (b).

**Conclusions:** FE analysis highlighted critical issues led by coupling elements with different values of  $\alpha_{th}$ . Some results have been confirmed by module testing. However, contact nonlinearities should be further investigated and considered in the model.

## References:

- Zienkiewicz O. C and Taylor R. L., *The Finite Element Method (vol. 2): Solid Mechanics*, 5<sup>th</sup> ed., Butterworth-Heinemann, Oxford (2000)
- A. Miozzo et al. Finite Element Approach for the Evaluation and Optimization of Silicide-Based TEG, *Proceedings of 11<sup>th</sup> ECT*, Noordwijk (2013)
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